TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (π -MOSVI)

2SK3797

Switching Regulator Applications

• Low drain-source ON resistance: RDS (ON) = 0.32Ω (typ.)

• High forward transfer admittance: $|Y_{fs}| = 7.5 \text{ S (typ.)}$

• Low leakage current: IDSS = 100 $\,\mu$ A (VDS = 600 V)

• Enhancement model: $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characte	eristic	Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	600	V	
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V _{DGR}	600	V	
Gate-source voltage		V _{GSS}	±30	V	
	DC (Note 1)	ID	13	А	
Drain current	Pulse (t = 1 ms) (Note 1)	I _{DP}	52		
Drain power dissipat	ion (Tc = 25°C)	P _D	50	W	
Single pulse avalanche energy (Note 2)		E _{AS}	1033	mJ	
Avalanche current		I _{AR}	13	А	
Repetitive avalanche energy (Note 3)		E _{AR}	5.0	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	

Unit: mm \$\delta 3.2\pm 0.2 \dots 0.15 \dots 0.69\pm 0.2 \dots 0.15 \dots 0.15 \dots 0.69\pm 0.2 \dots 0.69\pm 0.2 \dots 0.15 \dots 0.25 \dots 0.15 \dots 0.25 \dots 0.15 \dots 0.25 \dots 0.25

Weight: 1.7 g (typ.)

Thermal Characteristics

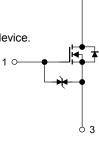
Characteristic	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	2.5	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C during use of the device.

Note 2: V_{DD} = 90 V, T_{Ch} = 25°C (initial), L = 10.7 mH, I_{AR} = 13 A, R_G = 25 Ω

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.



Ω 2



Electrical Characteristics (Ta = 25°C)

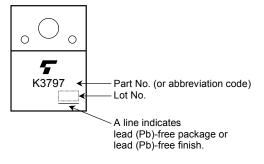
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Char	racteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I _{GSS}	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μΑ
Gate-source brea	akdown voltage	V (BR) GSS	$I_G=\pm 10~\mu A,~V_{DS}=0~V$	±30	_	_	V
Drain cutoff curre	ent	I _{DSS}	V _{DS} = 600 V, V _{GS} = 0 V	_	100		μА
Drain-source bre	akdown voltage	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	600	_	_	V
Gate threshold vo	oltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source ON	ain-source ON resistance $R_{DS (ON)}$ $V_{GS} = 10 \text{ V}, I_D = 6.5 \text{ A}$		V _{GS} = 10 V, I _D = 6.5 A		0.32	0.43	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 7.0 A	2.1	7.5	_	S
Input capacitance	put capacitance C _{iss}			_	3100	_	pF
Reverse transfer capacitance		C _{rss}	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		20	_	
Output capacitance		C _{oss}		_	270	_	
	Rise time	t _r	V_{GS} V_{OV} V		60	_	- ns
Switching time	Turn-on time	t _{on}			110	_	
Switching time	Fall time	t _f			50	_	
	Turn-off time	t _{off}	Duty \leq 1%, $t_W = 10 \ \mu s$	_	215	_	
Total gate charge		Qg		_	62	_	
Gate-source charge		Q _{gs}	$V_{DD} \simeq 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 13 \text{ A}$		40	_	nC
Gate-drain charge		Q _{gd}			22	_	

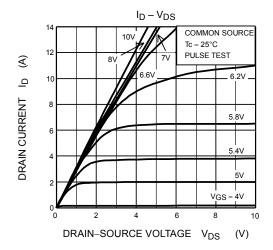
Source-Drain Ratings and Characteristics (Ta = 25°C)

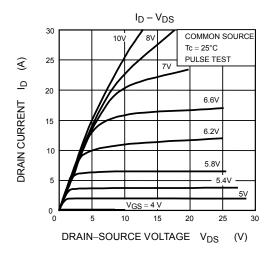
Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current	(Note 1)	I _{DR}	_			13	Α
Pulse drain reverse current	(Note 1)	I _{DRP}	_	_	_	52	Α
Forward voltage (diode)		V _{DSF}	$I_{DR} = 13 \text{ A}, V_{GS} = 0 \text{ V}$	-	_	-1.7	V
Reverse recovery time		t _{rr}	$I_{DR} = 13 \text{ A}, V_{GS} = 0 \text{ V},$	_	1050	_	ns
Reverse recovery charge		Q _{rr}	dl _{DR} /dt = 100 A/μs	_	15	_	μС

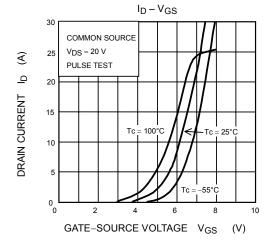
Marking

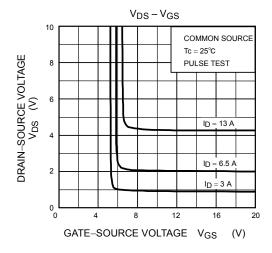


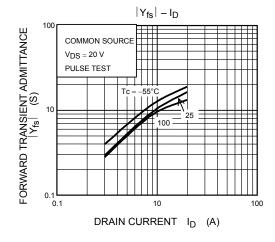
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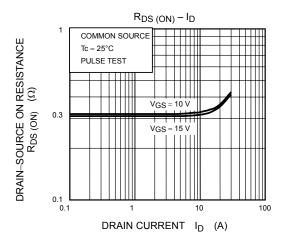




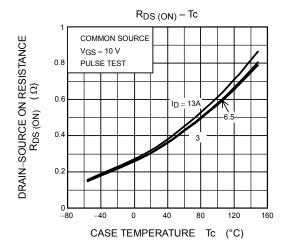


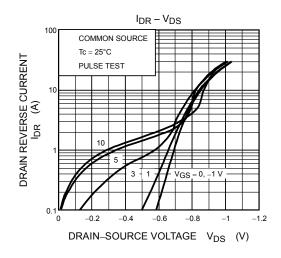


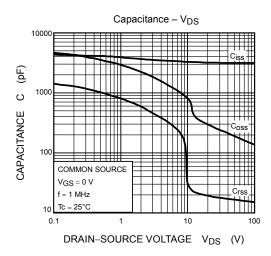


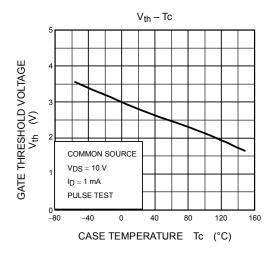


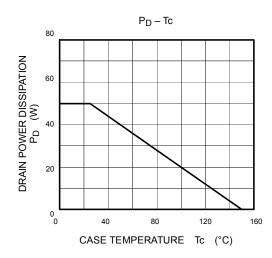
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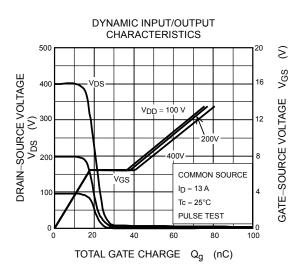


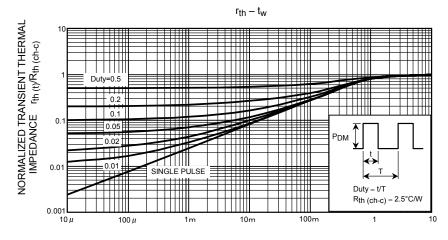




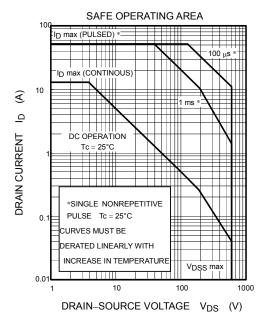


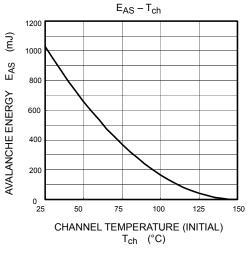


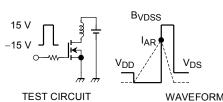




PULSE WIDTH t_w (s)







$$R_G = 25~\Omega$$

$$V_{DD} = 90~V,~L = 10.7 mH$$

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$

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